■ Lighting Color

White

LNJ037X8BRA

Hight Bright Surface Mounting Chip LED

ESS II Type

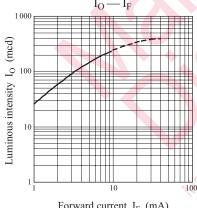
■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	P_{D}	40	mW	
Forward current	I_{F}	10	mA	
Pulse forward current *	I_{FP}	40	mA	
Reverse voltage	V _R	5	V	
Operating ambient temperature	T _{opr}	-30 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

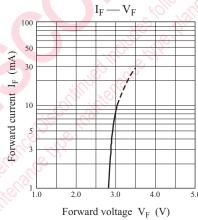
Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

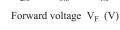
■ Electro-Optical Characteristics $T_a = 25$ °C

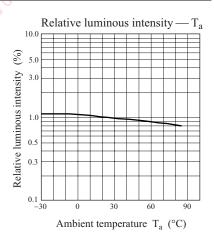
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	т	$I_F = 1 \text{ mA}$	18.0	29.0	45.0	mcd
	I _O	$(I_F = 5 \text{ mA})$	(80)	(150)	(205)	mcd
Reverse current	I_R	$V_R = 5 V$	YIC,	960	10	μΑ
Forward voltage	V_{F}	$I_F = 1 \text{ mA}$	2.6	2.8	3.0	V
Chromaticity coordinates	x	$I_F = 1 \text{ mA}$	0.220		0.281	_
	у	$I_F = 1 \text{ mA}$	0.187		0.272	



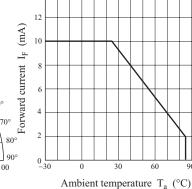


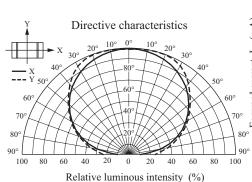






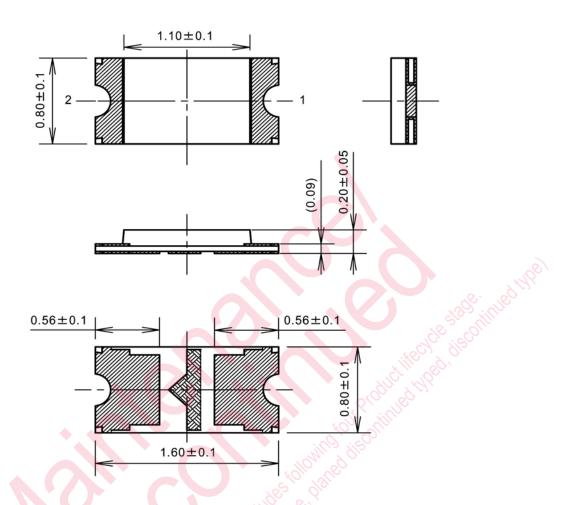
 $I_F - T_a$





LNJ037X8BRA Panasonic

■ Package (Unit: mm)



• Pin Name

2

- 1: Anode
- 2: Cathode

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